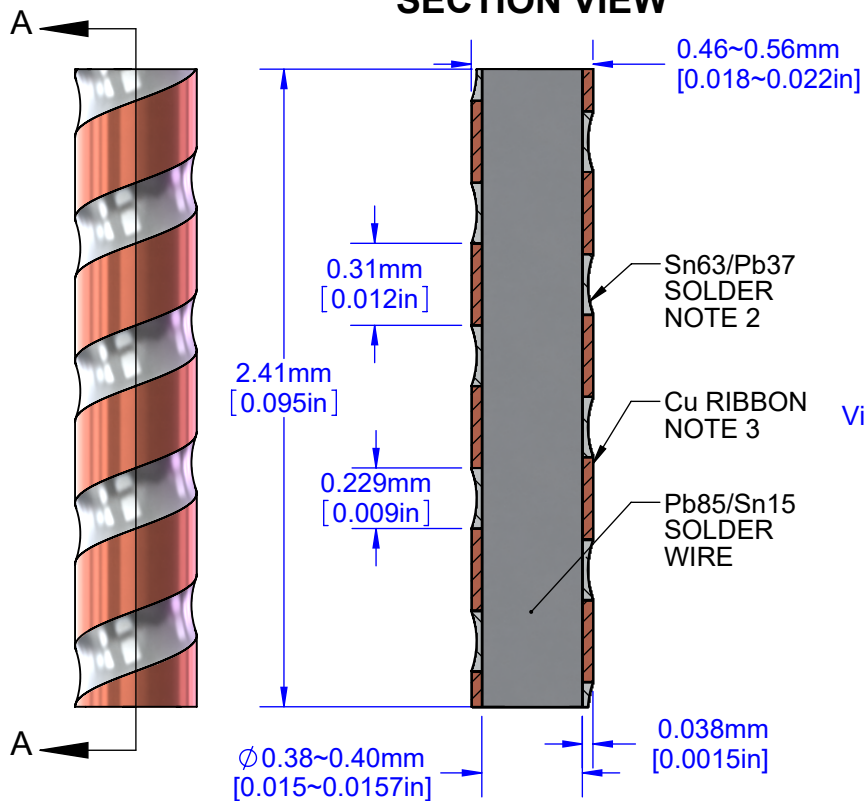
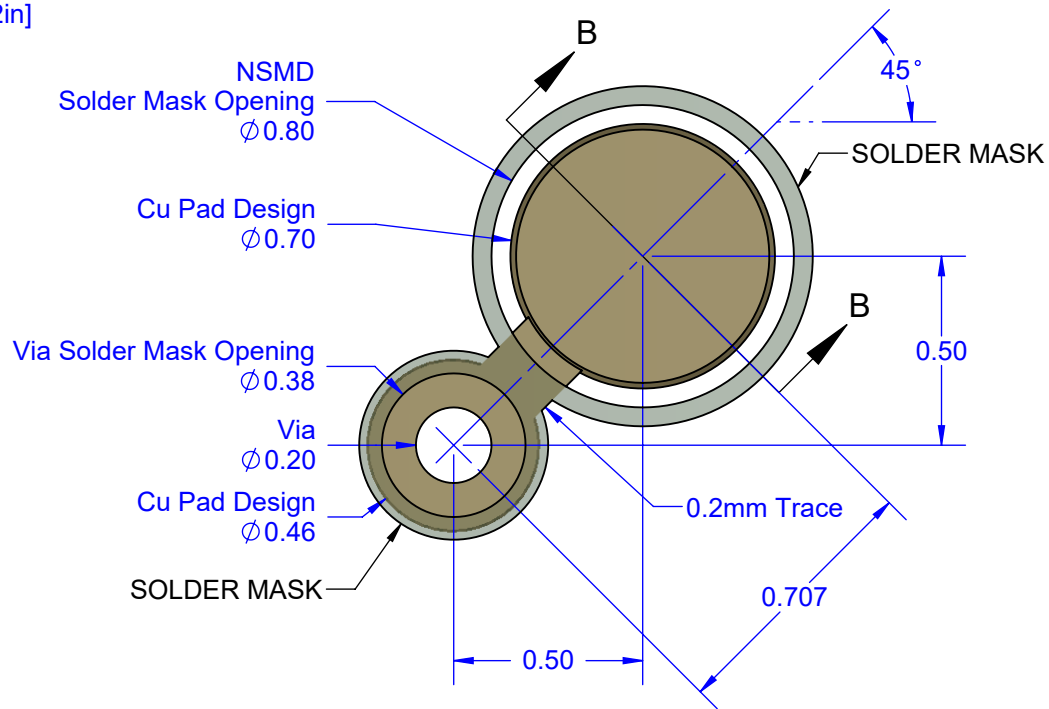


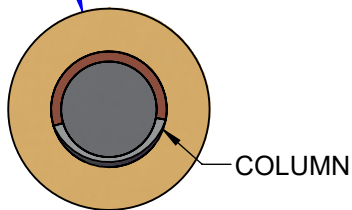
SECTION VIEW



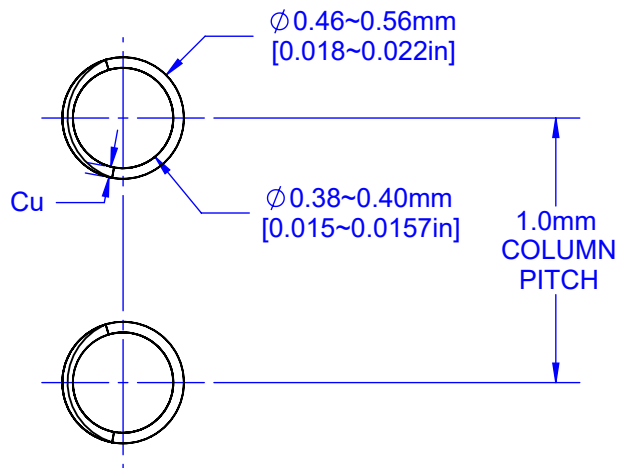
PCB LAND PATTERN (NOTE 4)



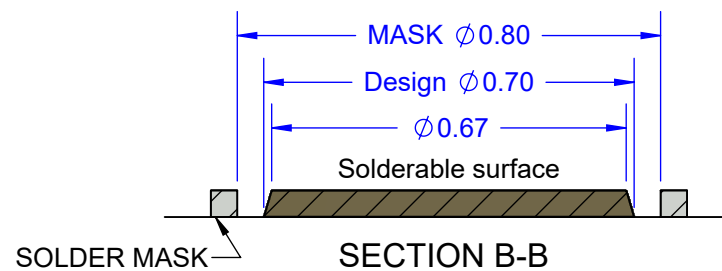
$\phi 0.80\pm 0.05$
CLGA PAD



CCGA PACKAGE PAD PLATING Ni-Au



Cu PAD SIDE VIEW



NOTES: (Unless Otherwise Specified).

- 1) DIMENSIONS IN mm [INCHES].
- 2) THICKNESS Sn63/Pb37 SOLDER COAT 6~25um [0.25~1.0mil].
- 3) Cu ALLOY C10100 - OFE (CDA-101). 99.99% PURE.
- 4) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.

APPROVALS	DATE	TopLine®			
DRAWN T. Au	04/17/16				
ENG M. Hart	04/17/16	TITLE CG8515C20x95 CCGA SOLDER COLUMN			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		35:1	A	852095	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 1
REVISED					